




APPLICABLE STANDARD					
Rating	Operating Temperature Range	-40 °C to 140 °C ⁽¹⁾	Storage Temperature Range	-10 °C to 60 °C ⁽²⁾	
	Voltage	125 V AC ⁽³⁾	Storage Humidity Range	Relative humidity 60% max (Not dewed)	
	Current	0.5 A	Operating Humidity Range	Relative humidity 85% max (Not dewed)	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	
QT		AT			
CONSTRUCTION					
General Examination		Examined visually and with a measuring instrument.		According to the drawing.	x
Marking		Confirmed visually.			x
ELECTRICAL CHARACTERISTICS					
Contact Resistance		Measured at 100 mA MAX.(DC or 1000Hz)		65m Ω MAX.	x
Insulation Resistance		Measured at 250 V DC.		1000 MΩ MIN.	x
Voltage Proof		375 V AC applied for 1 min.		No flashover or breakdown.	x
MECHANICAL CHARACTERISTICS					
Mating and Unmating Forces		Measured with an applicable connector.		Mating Force: 20 N MAX. Unmating Force: 2.2 N MIN.	x
Mechanical Operation		Mated and unmated 10 times.		①Contact Resistance : 75m Ω MAX. ②No damage, cracks or looseness of parts.	x
Vibration		Frequency 50~100 → 100~150 → 150~300Hz Acceleration 98 → 98~294 → 294 m/s ² 1 cycle 3 min 3 h for 3 axial directions ⁽⁴⁾		①No electrical discontinuity of more than 1 μs. ②No damage, cracks or looseness of parts.	x
Shock		Acceleration 980 m/s ² , duration of pulse 6 ms at 3 times for 3 axial directions.			
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 60±2 °C, 90 ~ 95 %, 1000 h.		①Contact Resistance : 75m Ω MAX. ②Insulation Resistance : 1000 MΩ MIN.  ③No damage, cracks or looseness of parts.	x
Rapid Change of Temperature		Temperature -40 → +140 °C Time 30 → 30 min. under 1000 cycles. (Relocation time to chamber : within 2~3 MIN)			x
Cold		Exposed at -40°C, 1000 h		①Contact Resistance : 75m Ω MAX.	x
Dry Heat		Exposed at 140°C, 1000 h		②No damage, cracks or looseness of parts.	x
Sulfur Dioxide		Exposed at 40±2°C, 80±5%RH, 25±5ppm  for 96 h.		Contact Resistance : 75m Ω MAX.	x
Resistance to Soldering Heat		1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 		No deformation of case of excessive looseness of the terminal.	x
Solderability		Soldered at solder temperature 240±3°C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x
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